Advantages of the LLP Package

KEY BENEFITS

- Only visual inspection is needed: side solderability eliminates the need for X-ray inspection
- Enables more cost-effective production
- Compatible with most common footprints; no design-in restrictions
- Wide variety of product types and case sizes
- Offers more space inside of package, allowing larger die area or more chips to be used
  - Hosts up to eight arrayed diodes
- ESD protection diodes and EMI filter devices are available in LLP Packages
  - $V_{ESD}$ up to 30 kV
  - $C_D$ of less than 1 pF
- EMI filter portfolio
  - Typical cut-off frequency of 130 MHz
  - Input loss down to 1 dB

RESOURCES

- For technical questions contact ESDProtection@vishay.com
- Material categorization: For definitions of compliance please see http://www.vishay.com/doc?99912
## Advantages of the LLP Package

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<tr>
<th>FOOTPRINT</th>
<th>SOLDERING PROFILE</th>
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**Legend:**
- Lead / Pad
- Solderpad / Footprint
- Solder meniscus

Visual inspection possible due to solder meniscus. No X-ray needed.